

#### REMARKS

Applicants respectfully request favorable reconsideration of this application.

Applicants submitted a certified copy of the priority document in the prior Application No. 10/242,720 on October 29, 2002. Confirmation of receipt of the priority document is respectfully requested in the next Office Action.

Claims 14-22 are pending.

Regarding the objection to Claim 14 at page 2 of the Office Action, Applicants respectfully submit that support for the Claim 14 limitation, "wherein, in said wiring substrate provided in said step (b), the pitch of said plural salient electrodes is smaller than the pitch of said leads at the portions corresponding respectively to the plural salient electrodes," is provided at page 16, line 20 through page 18, line 12; FIG. 9; and original Claim 12 at page 26, lines 10-12 of Applicants' disclosure. For example, Applicants' specification provides:

"As shown in FIG. 9, moreover, since the back side of the film substrate 3 is pushed with the bonding tool 105 in the down-set state of the chip 1, the insulating film 4 is pulled at positions close to the four corners of the chip mounting area C, so that the pitch of the inner leads 5a becomes wider than that before the bonding. That is, the influence caused by the insulating film 4 being pulled is greater than the influence caused by thermal expansion of the same film. Therefore, at the portions close to the four corners of the chip mounting area C where the final pitch of the inner leads 5a

becomes wider than the pitch before the bonding,  
a (-) correction is made to the pitch of the  
inner leads 5a.

By so doing, when the insulating film 4 in the  
chip mounting area C expands with the heat  
applied thereto from the bonding tool 105, or  
shrinks in appearance, the inner leads 5a and the  
Au bumps 2 to be connected thereto become  
positionally coincident with each other at a high  
accuracy . . ."

Specification, page 17, line 14 to page 18, line 7 (underlines added).

Because the pitch of the inner leads 5a is "wider than the pitch before the bonding" due to the pulling of the insulating film 4 and requires correction for bonding "positionally coincident" with the electrodes 2, it follows therefrom that the pitch of said plural salient electrodes is smaller than the pitch of said leads at the portions corresponding respectively to the plural salient electrodes as recited in Claim 14.

Accordingly, it is clear that Claim 14 is enabled by Applicants' disclosure.

In the Office Action, Claim 14 was rejected under the judicially-created doctrine of nonstatutory double patenting with respect to Claim 12 of U.S. Patent No. 6,699,737. Applicants respectfully request this rejection be withdrawn in view of the Terminal Disclaimer submitted herewith.

Claims 14-22 were also rejected under 35 U.S.C. § 102 over Mita. This rejection is respectfully traversed.

Claim 14 recites, *inter alia*, that, in the wiring substrate provided in said step (b), the pitch of the salient electrodes is smaller than the pitch of the leads at the portions corresponding respectively to the salient electrodes. It is apparent that Mita does not teach or disclose at least this feature of Claim 14.

For example, Mita teaches external electrodes 2 having a pitch of 0.166mm. See Mita, para. [0155] and FIG. 4B. Mita's joining portions 9A of inner leads 9, to which the external electrodes 2 are bonded, are also disclosed as having the same pitch of 0.166mm. See Mita, para. [0157] and FIG. 5A. Therefore, Mita does not teach or suggest that the pitch of the salient electrodes is smaller than the pitch of the leads at the portions corresponding respectively to the salient electrodes, as recited in Claim 14.

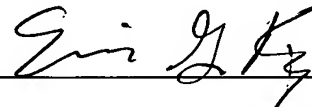
Accordingly, Applicants respectfully request the rejection be withdrawn.

In view of the foregoing, Applicants respectfully request a prompt Notice of Allowance.

The Commissioner is hereby authorized to charge to Deposit Account No. 50-1165 (T3844-908095US02) any fees under 37 C.F.R. §§ 1.16 and 1.17 that may be required by this paper and to credit any overpayment to that Account. If any extension of time is required in connection with the filing of this paper and has not been requested separately, such extension is hereby requested.

Respectfully submitted,

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